RESINIFY — INSTRUCTIONS FOR USE (IFU)

HighTemp 230 (RT-HT230) — Extreme-Temperature Engineering Resin For High-Performance Fixtures, Thermal Tooling & Applications up to 230°C

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1. Product Overview

HighTemp 230 is an **extreme heat-resistant engineering resin** designed for applications requiring high thermal stability, strong mechanical retention at temperature, and minimal deformation under load. Ideal for molds, industrial fixtures, electronic housings, and high-heat environments.

2. Printer Compatibility

- LCD / mSLA / DLP printers
- 385–405 nm wavelength
- Designed for advanced engineering platforms

3. Printing Instructions

Parameter	Recommended
Layer Height	50–100 µm
Normal Exposure	3.4–4.4 sec
Bottom Exposure	50–65 sec
Bottom Layers	6–8
Lift Speed	Medium
Light-Off Delay	Enabled

Support Tips:

- Use heavy supports for thermal tooling geometries.
- Angle 20–30° to control peel forces and strengthen print anchoring.
- Reinforce areas with mass to prevent micro-warping.

4. Cleaning Instructions

- Wash **2–3 minutes** using IPA or resin cleaner.
- Allow complete drying — essential for high-temperature stability.
- Avoid excessive wash times.

5. Post-Curing Instructions

- UV cure **25–35 minutes**.
- **Mandatory heat cure to achieve peak HDT:**
    i. **Step 1:** 60°C for 30 minutes.
    ii. **Step 2:** 110–120°C for 30 minutes.
- Controlled cooling prevents thermal stress cracking.

6. Usage Guidelines

- Ideal for molds, high-heat jigs, industrial guides, and thermal housings.
- Can withstand extended exposure to high temperatures.
- Machine or sand surfaces after curing for best finish.
- Avoid over-curing which may increase brittleness.

7. Safety & Disposal

- Wear gloves, mask, and eye protection.
- Cure all waste resin prior to disposal.
- Dispose of IPA according to local standards.